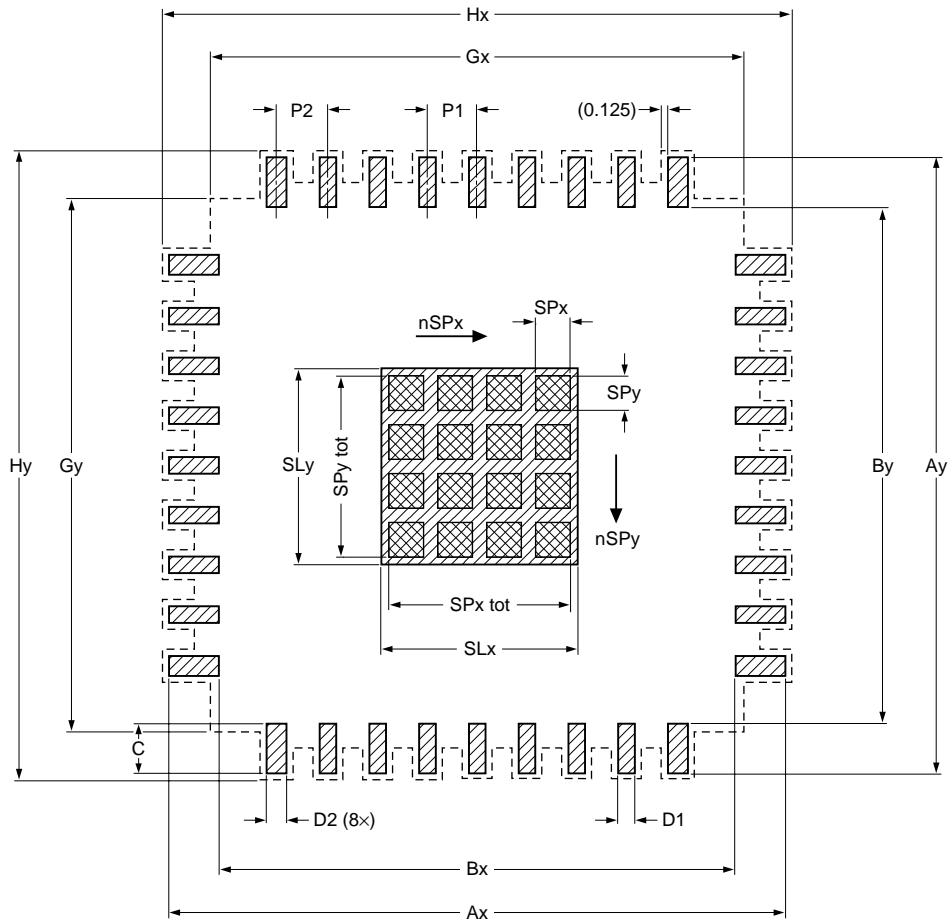





Footprint information for reflow soldering of HTQFP48 package

SOT545-2



Generic footprint pattern

Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

nSPx	nSPy
4	4

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy	SLx	SLy	SPx tot	SPy tot	SPx	SPy
0.500	0.560	9.700	9.700	7.300	7.300	1.200	0.280	0.400	7.500	7.500	9.950	9.950	4.800	4.800	4.700	4.700	0.800	0.800